

Product/Process Change Notification

N° 2021-129-A

Dear customer,

please find attached our Infineon Technologies AG PCN:



Several changes affecting product TLE7268SK

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2022-01-10.
- Infineon aligns with the widely-recognized JEDEC STANDARD “JESD46”, which stipulates: “Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.” Notwithstanding the aforesaid individual agreements shall prevail.

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.



On 16 April 2020, Infineon acquired Cypress.

We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance.

For further details, please visit our website:

<https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/>

Infineon Technologies AG

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Chairman of the Supervisory Board: Dr. Wolfgang Eder

Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Constanze Hufenbecher, Dr. Sven Schneider

Registered Office: Neubiberg

Commercial Register: München HRB 126492

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Products affected

Please refer to attached affected product list 1_cip21129_A

Detailed change information

Subject: Several changes affecting product TLE7268SK

Reason/Motivation: Expansion of wafer production and wafer test to assure continuity of supply and enable flexible manufacturing. Change of assembly process to harmonize the DSO package platform process.

Description

	<u>Old</u>	<u>New</u>
PROCESS - WAFER PRODUCTION: Move all or parts of production to a different wafer fab site.	Infineon Technologies Austria AG, Villach, Austria	Infineon Technologies Austria AG, Villach, Austria
		AND Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia
PROCESS - ASSEMBLY: Change of lead frame finishing material / area (internal)	Ag spot	Ag spot
		AND Ag ring
PROCESS - ASSEMBLY: Die attach material	EN4900	EN4900
		AND AB3230
TEST FLOW: Move of all or part of electrical wafer test and/or final test to a different test site.	Infineon Technologies Austria AG, Villach, Austria	Infineon Technologies Austria AG, Villach, Austria
		AND Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia

Product identification

Wafer lot numbers from Villach start with VExxxxxx.
 Wafer lot numbers from Kulim with 1Exxxxxx
 Traceability assured via date code.
 No change in SP ordering number

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Anticipated impact of change

Based on the qualification performed, Infineon does not expect any negative impact on quality, function and reliability. No change in form, fit and function expected.

DeQuMa-ID(s): SEM-PW-13 / SEM-PA-04 / SEM-PA-07 / SEM-TF-01

Attachments

1_cip21129_A affected product list

Time schedule

Final qualification report	available
First samples available	on request
Intended start of delivery [1]	2022-06-15
Last order date (LOD) [2]	2022-06-15
Last delivery date (LDD) [3]	2023-06-15

[1] provided date or earlier after customer approval

[2] Last time buy volume to be placed latest until LOD

[3] Delivery of new product can be earlier (see Intended start of delivery) and depends on approval

If you have any questions, please do not hesitate to contact your local sales office.